

DEVICE	Package Type	Material	Supplier	Type	Compisition	CAS No.	% of weight	Appendix	Weight(mg)	ICP报告	MSDS
LSS3307-18D	SOP8L	Die	/	/	Silicon	7440-21-3	100.000%	/	1.0	/	/
		Lead Frame	HTBJ	90×90A-12P ERC	Copper	7440-50-8	96.630%	NA	21.3		
					Iron	7439-89-6	2.200%				
					Phosphorus	7723-14-0	0.065%				
					Zinc	7440-66-6	0.100%				
					Lead	7439-92-1	0.005%				
					Silver	7440-22-4	1.000%				
		Epoxy	汉高	8200T	Silver	7440-22-4	84.400%	NA	1.0		
					Acrylate Monomer	proprietary	15.000%				
					BMI Resin	proprietary	0.300%				
					2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3	0.300%				
		Mold Compound	SDMSZ	CEL-9220HF10TS(LS)	Epoxy Resin 1	Trade secret	2.5000%	NA	46.0		
					Epoxy Resin 2	Trade secret	2.5000%				
					Epoxy Resin 3	Trade secret	2.5000%				
					Hardener	Trade secret	5.0000%				
					Catalyst	Trade secret	0.5000%				
					Carbon black	1333-86-4	0.2000%				
					Amorphous silica1	60676-86-0	78.8000%				
					Amorphous silica2	7631-86-9	8.0000%				
		Wire	MKE	20umAuPdCu	Copper	7440-50-8	98.80%	NA	0.7		
Palladium	7440-05-3				1.000%						
Gold	7440-57-5				0.200%						
Plating	Aisen	Tin	Sn	7440-31-5	99.990%	NA	2.0				
			Others	/	0.010%						
								Total=	72.0		